

IN THE SPECIFICATION

Please amend the paragraph extending from page 3, last line, to page 4, line 7, as follows:

(6) Below the upper frame 109, a lower frame 112 is provided, and between the upper frame 109 and the lower frame 112, a semiconductor element 103 mounted on the surface of the flexible substrate 102 is interposed so as to face downward. Namely, the semiconductor element 103 is stored in a recessed part of the lower frame 112, and the flexible substrate 102 is curved so as to have a cross section of substantially C-shape.

Please amend the paragraph extending from page 4, line 14, to page 5, line 7, as follows:

In the foregoing liquid crystal module 100, if the connection part 113 is formed on the lower glass substrate 107, the semiconductor element 103 would be projected to the inside of the module main body. Conventionally, the above structure of forming the connection part 113 on the lower glass substrate 107 is adopted. In this conventional structure, however, the number of connection points for leading transparent wiring formed on the upper glass substrate 106 to the lower glass substrate 107 increases, and consequently, an area occupied by the connection points increases. For this reason ~~reasons~~, it is difficult to realize a compact size structure for an increased number of pixels. Therefore, in recent years, the structure wherein the connection part is formed on the upper glass substrate 106 is generally adopted for the reason that the number of connection points can be reduced by forming the transparent wiring of the lower glass substrate 107 in the upper part.

Please amend the paragraph extending from page 6, line 6, to page 6, line 16, as follows:

That is, in the liquid crystal module 100 illustrated in Figure 11, the connection part 113 is formed on the upper glass substrate 106 of the liquid crystal panel 108. Therefore, in the structure of bending the flexible substrate 102, the semiconductor element 103 is inevitably projected to the outside. Consequently, a spacing for the thickness corresponding to the thickness of the semiconductor element 103 is required between the flexible substrate 102 and the main substrate 114, and a thinner structure is therefore difficult to be achieved.

Please amend the paragraph extending from page 12, line 10, to page 13, line 2, as follows:

As illustrated in Figure 1, a liquid crystal module 1 in accordance with the present embodiment includes a light-directing plate 11 (lighting means) formed above a frame 20 via a reflective sheet 11a. Further, above the light-directing plate 11, formed via a diffusing plate 11b is a liquid crystal panel 10 (member to be connected) ~~composed~~ comprised of an upper glass substrate 13 and a lower glass substrate 14 interposed between polarization plates 12. Between the upper glass substrate 13 and the lower glass substrate 14, a liquid crystal layer (not shown) and an electrode 15 are interposed. The upper glass substrate 13 is formed longer than the lower glass substrate 14, and the electrode 15 is mounted on the upper glass substrate 13 so as to be exposed and extended facing downward. Further, an LED (Light Emitting Diode) 16 is provided as a back light (lighting means) along a side face of the light directing plate 11.

Please amend the paragraph extending from page 17, line 16, to page 17, line 25, as follows:

The flexible substrate 3 is constituted by a flexible thin film tape made of polyimide resin. Here, this flexible substrate 3 needs to be ~~bent~~ bend in a U-shape at the end portions as will be described later. It is therefore preferable to select the thickness of the flexible substrate 3 to be not more than 40 μm . However, a suitable thickness of the flexible substrate 3 is not limited to the above range, and may be varied to be suited for a material adopted.